

 Tagged (0)

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[(semiconductor and redistribution) and peripheral) and "line width"

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	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20020014691 A1	20020207	16	MULTIPLE LINE GRID ARRAY PACKAGE	257/697	
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6315200 B1	20011113	296	Encoded data card reading system	235/454	235/462.01; 235/462.1; 235/462.2
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6204562 B1	20010320	6	Wafer-level chip scale package	257/777	257/723; 257/775; 257/776
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6093243 A	20000725	154	Semiconductor device and its fabricating method	117/8	117/9; 438/250; 438/251
5	<input type="checkbox"/>	<input type="checkbox"/>	US 6066872 A	20000523	153	Semiconductor device and its fabricating method	257/309	257/534
6	<input type="checkbox"/>	<input type="checkbox"/>	US 6043109 A	20000328	7	Method of fabricating wafer-level package	438/113	438/109; 438/118
7	<input type="checkbox"/>	<input type="checkbox"/>	US 5994766 A	19991130	12	Flip chip circuit arrangement with redistribution layer that minimizes	257/659	257/664; 257/691
8	<input type="checkbox"/>	<input type="checkbox"/>	US 5879447 A	19990309	152	Semiconductor device and its fabricating method	117/8	117/9; 117/930
9	<input type="checkbox"/>	<input type="checkbox"/>	US 5582640 A	19961210	154	Semiconductor device and its fabricating method	117/8	117/930; 438/166; 438/167
10	<input type="checkbox"/>	<input type="checkbox"/>	US 5391912 A	19950221	36	Semiconductor device having polycrystalline silicon region forming a	257/588	257/486; 257/627; 257/628
11	<input type="checkbox"/>	<input type="checkbox"/>	US 5227660 A	19930713	37	Semiconductor device	257/588	257/577; 257/627; 257/628

EAST - [Untitled1:1]

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Pending
Active
L1: [2237] semiconductor and redistribution
L2: [292] 1 and peripheral
L3: [0] 2 and "interconnect line"
L4: [13] 2 and "line width"
Failed
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[804] "quad flat pack"

DB: USPAT, US-PGPUB, EPO, JPO, DERWENT, IBM
Default operator: OR
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2 and "line width"

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